

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROSHI SASO	06/25/2018
TAKESHI MORIMOTO	06/25/2018
RECEIVING PARTY DATA	
Name:	SANSHA ELECTRIC MANUFACTURING CO., LTD.
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City:	OSAKA-SHI, OSAKA
State/Country:	JAPAN
Postal Code:	533-0031
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16025396
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ATTORNEY DOCKET NUMBER:	D3301-00237
NAME OF SUBMITTER:	JOSEPH A. POWERS, ESQUIRE
SIGNATURE:	/Joseph A. Powers/
DATE SIGNED:	07/02/2018
Total Attachments: 2	
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ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned, Hiroshi Saso of Osaka-shi, Osaka-fu, Japan; and Takeshi Morimoto of Osaka-shi, Osaka-fu, Japan;

Hereby sell, assign and transfer to Sansha Electric Manufacturing Company, Limited, a corporation of Japan, having a place of business at 1-56, Nishiawaji 3-chome, Higashiyodogawa-ku, Osaka-shi, Osaka-fu, Japan, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled

Power Supply Apparatus

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements, and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

The undersigned declare further that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of this assignment, patent or patent application and any patent issuing thereon.

Date : JUN. 25. 2018

Hiroshi Saso

Hiroshi Saso

Date : JUN. 25. 2018

T. Morimoto

Takeshi Morimoto